

	Type	L #	Hits	Search Text	DBs	Time Stamp
1	IS&R	L3	3256	(257/666).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/17 15:23
2	BRS	L7	2	(ground adj3 voltage) same (lead adj3 frame) same encapsulat\$3 same (plastic or epoxy or resin) same connect\$3	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/17 15:24
3	BRS	L8	0	(lead adj3 fram) near3 (fold\$4) near3 (die or dice or IC or chip or chips or device or devices)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/17 15:34
4	BRS	L9	14	(encapsulat\$4) same (plastic or epoxy) same (ground adj3 voltage)	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/17 15:47
5	IS&R	L10	859	(257/696).CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/17 16:20

	Type	L #	Hits	Search Text	DBs	Time Stamp
6	IS&R	L11	1407	(257/692) .CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/17 16:21
7	IS&R	L12	608	(438/124) .CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/17 16:49
8	IS&R	L13	627	(438/126) .CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/17 17:45
9	IS&R	L14	418	(257/684) .CCLS.	USPAT; US-PGP UB; EPO; JPO; DERWEN T; IBM_TD B	2003/05/17 18:02

US-PAT-NO: 5891760

DOCUMENT-IDENTIFIER: US 5891760 A

TITLE: Lead frame with electrostatic  
discharge protection

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Detailed Description Text - DETX (24):

In step 208, die may be mounted on the lead frame at a die attach area, such as a die attach pad, using conventional techniques well known to those skilled in the art. Alternatively, the die may be attached to the lead frame by a double sided polyimide tape. In step 210, the electrostatic discharge protection polymer on the lead undergoes curing. In one embodiment, steps 208 and 210 can be carried out simultaneously, i.e. the polymer is cured while the die is being mounted on the lead frame. In step 212, the die is electrically coupled to the leads, which is typically done by a plurality of bonding wires that connect associated ones of the bond pads on the die to associated ones of the leads. In step 214, at least one of the leads in the lead frame is connected to ground voltage establishing ground plane. Step 216 includes encapsulating the die, the bonding wires, the device, the grounding wires and a portion of the leads to provide a protective package and leaving exposed a portion of the leads to facilitate electrical connection of the integrated circuit package to external circuitry. A commonly used encapsulation material is epoxy since it can be easily and cost effectively applied by transfer

molding.